

1. Record Nr.	UNINA9910699648903321
Autore	Fuller Robert L
Titolo	Closed Brayton Cycle power conversion unit for fission surface power, phase I final report [[electronic resource] /] / Robert L. Fuller
Pubbl/distr/stampa	Cleveland, Ohio : , : National Aeronautics and Space Administration, Glenn Research Center, , [2010]
Descrizione fisica	1 online resource (v, 64 pages) : illustrations
Collana	NASA/CR-2010-215673
Soggetti	Brayton cycle Closed cycles Fission Power converters Fluid flow
Lingua di pubblicazione	Inglese
Formato	Materiale a stampa
Livello bibliografico	Monografia
Note generali	Title from title screen (viewed on March 7, 2011). "June 2010."

2. Record Nr.	UNINA9911003689103321
Autore	Prall Kirk
Titolo	CMOS Plasma and Process Damage / / by Kirk Prall
Pubbl/distr/stampa	Cham : , : Springer Nature Switzerland : , : Imprint : Springer, , 2025
ISBN	3-031-89029-9
Edizione	[1st ed. 2025.]
Descrizione fisica	1 online resource (XIX, 466 p. 399 illus., 368 illus. in color.)
Disciplina	621.3815
Soggetti	Electronic circuit design Embedded computer systems Solid state physics Electronics Design and Verification Embedded Systems Electronic Devices
Lingua di pubblicazione	Inglese
Formato	Materiale a stampa
Livello bibliografico	Monografia
Nota di contenuto	Chapter 1. BACKGROUND -- Chapter 2. THE ANTENNA EFFECT -- Chapter 3. DIODE AND TRANSISTOR PROTECTION -- Chapter 4. SIGNATURES OF PROCESS DAMAGE -- Chapter 5. ELECTRICAL SIGNATURES OF PROCESS DAMAGE -- Chapter 6. LATENT DAMAGE AND RELIABILITY DEGRADATION -- Chapter 7. ATOMIC-LEVEL DEFECTS AND ELECTRICAL EFFECTS -- Chapter 8. TECHNOLOGY SPECIFIC PROCESS DAMAGE -- Chapter 9. COMMON SOURCES OF PROCESS DAMAGE -- Chapter 10. INLINE PROCESS DAMAGE MEASUREMENTS -- Chapter 11. PROCESS DAMAGE TEST STRUCTURES -- Chapter 12. DESIGN RULES RELATED TO PROCESS DAMAGE -- Chapter 13. PARAMETRIC DAMAGE TESTING STRATEGY AND PROCEDURES -- Chapter 14. THE ROLE OF HYDROGEN -- Chapter 15. METALLIC DEFECTS -- Chapter 16. MOBILE ION CONTAMINATION -- Chapter 17. FIXED CHARGE.
Sommario/riassunto	This book discusses the complex technology of building CMOS computer chips and covers some of the unusual problems that can occur during chip manufacturing. Readers will learn how plasma and process damage results from the high-energy processes that are used in chip manufacturing, causing harm to the chips, functional failure and reliability problems. Provides an up-to-date, single-source reference

on CMOS plasma and process damage, for engineers from all disciplines Offers concise, comprehensive coverage, discussing real problems with necessary background for working engineers Applies to design, layout, mask making, lithography, process and device engineering, testing and reliability.
